



Ref No.: FSM/CC/RFQ/AMC/2019-20/05

Subject: RFQ for Dell Care pack/ Extended warranty (AMC) of DELL Servers for next 1 year (2019-20)

Sealed tenders are invited from OEM's/ or their eligible Service Provider Companies / Firms dully authorized by OEM, for the award of on-site AMC (Dell Care Pack) of Dell R720 Servers.

Interested vendors are requested to submit their proposal in a closed envelope mentioning "Quotation for Care pack/ Extended warranty (AMC) of DELL Servers (2019-20)".

The General Terms & Conditions are attached as **Annexure-1**.

Tender Issue Date: 07-Aug-2019

Tender Closing Date: 16-Aug-2019

*udg Kumar
6/08/2019*

Issued by:

Manager (Systems)

FORE School of Management
B-18, Qutab Institutional Area,
New Delhi – 110016

General Terms & Conditions of Bid:

1. Bid Submission: Two Bid System (Technical Bid and Financial Bid):

- A. The two bid system will be followed for this tender. Bidder is advised to carefully read this tender document before submitting their bid. In this system bidder must submit his offer in two separate sealed envelopes under main envelop as explained below:
- I. Envelope No.1 "Technical Bid"
 - II. Envelope No.2 "Financial Bid"
- B. Bidders will be selected by the following steps given as under:
- I. Short-listing of eligible vendors satisfying the technical qualification requirements laid in this tender document.
 - II. The Financial Bids of only those bidders will be opened whose technical bids would clear the technical evaluation.
 - III. Selection of bidder as the Service Provider based on the lowest price quotes and meets the commercial qualification requirements from the technically qualified short listed vendors.

1A. Technical Bid:

- A. OEM's/ or their eligible Service Provider Companies / Firms dully authorized by OEM. Document required for the same.
- B. Copy of PAN card
- C. Certificates of registration for GST

1B. Financial Bid:

- A. The rate may be quoted for Financial Bid in a separate envelope mentioning "Financial Bid" in a sealed cover with signature of authorized person.
- B. The Financial Bid should contain the rate against each item separately. All taxes and duties, if any must be indicated.



Submission Deadlines:

- A. **Submission Deadlines:** Interested bidders send to their offer in a closed envelop mentioning “**Quotation for Care pack/ Extended warranty (AMC) of DELL Servers**” on the cover, by courier or drop it in the box kept with security guard of FORE School of Management latest by 11:00 A.M. on or before 16th August 2019.
- B. **Submission Delivery Address:** The delivery address to be used for all submissions is

Uday Kumar

Manager (Systems)

FORE School of Management

B-18, Qutab Institutional Area, New Delhi – 110016

Phone No.: +91-11-41242445, Email: uday@fsm.ac.in

- C. Submission Questions and Clarifications:

You may contact -

Uday Kumar

Call: +91-11-41242445 or Email to uday@fsm.ac.in

Electronic Submission: Electronic submission in response to this Request for Proposal will not be accepted. All submission must be on paper.

Other Terms & Conditions

- A. **Purchase Order:** The Purchase Order will be released for those who have successfully qualified the Technical Bid and Financial Bid. The Purchase Order has to be accepted by the bidder signing and returning an acknowledgement copy of it within 5 working days.
- B. **Payment Term:** The Payment will be made within 10-15 days of delivery of the certificate of Care Pack/ Extended Warranty & Submission of Invoice. **The detail hardware inventory is mentioned in Annexure-2.**

Uday Kumar



Annexure-2

List of Servers for Care pack AMC

S. No.	Model	Serial No.	Purchase Date
1	Dell R720	H4BYFY1	17-09-2013
2	Dell R720	FJBYFY1	17-09-2013
3	Dell R720	CJBYFY1	17-09-2013

Uday Kumar